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United States Patent [19]

Simek et al.

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[54] **FRONT PANEL FOR ENCLOSING ELECTRONIC CIRCUIT PACKS**

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D. 308,679 6/1990 Reshanov D13/177
 D. 312,611 12/1990 Watson et al. D13/158
 2,620,080 12/1952 Tomlin 220/3.4
 3,058,020 10/1962 Balan 174/66
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[73] Assignee: **Motorola, Inc.**, Schaumburg, Ill.
 [**] Term: **14 Years**

Primary Examiner—A. Hugo Word

[21] Appl. No.: **19,158**

[57] CLAIM

[22] Filed: **Feb. 24, 1994**

The ornamental design for a front panel for enclosing electronic circuit packs, as shown and described.

[52] U.S. Cl. **D13/177; D10/125**

DESCRIPTION

[58] **Field of Search** D13/158, 177;
 200/43.22, 333, 334; 439/519, 528, 536;
 174/66, 67; 220/3.4, 3.8, 241, 242; D10/103,
 125

FIG. 1 is a front, top, and right side perspective view of a front panel for enclosing electronic circuit packs showing our new design;

FIG. 2 is a left side elevational view thereof; and,

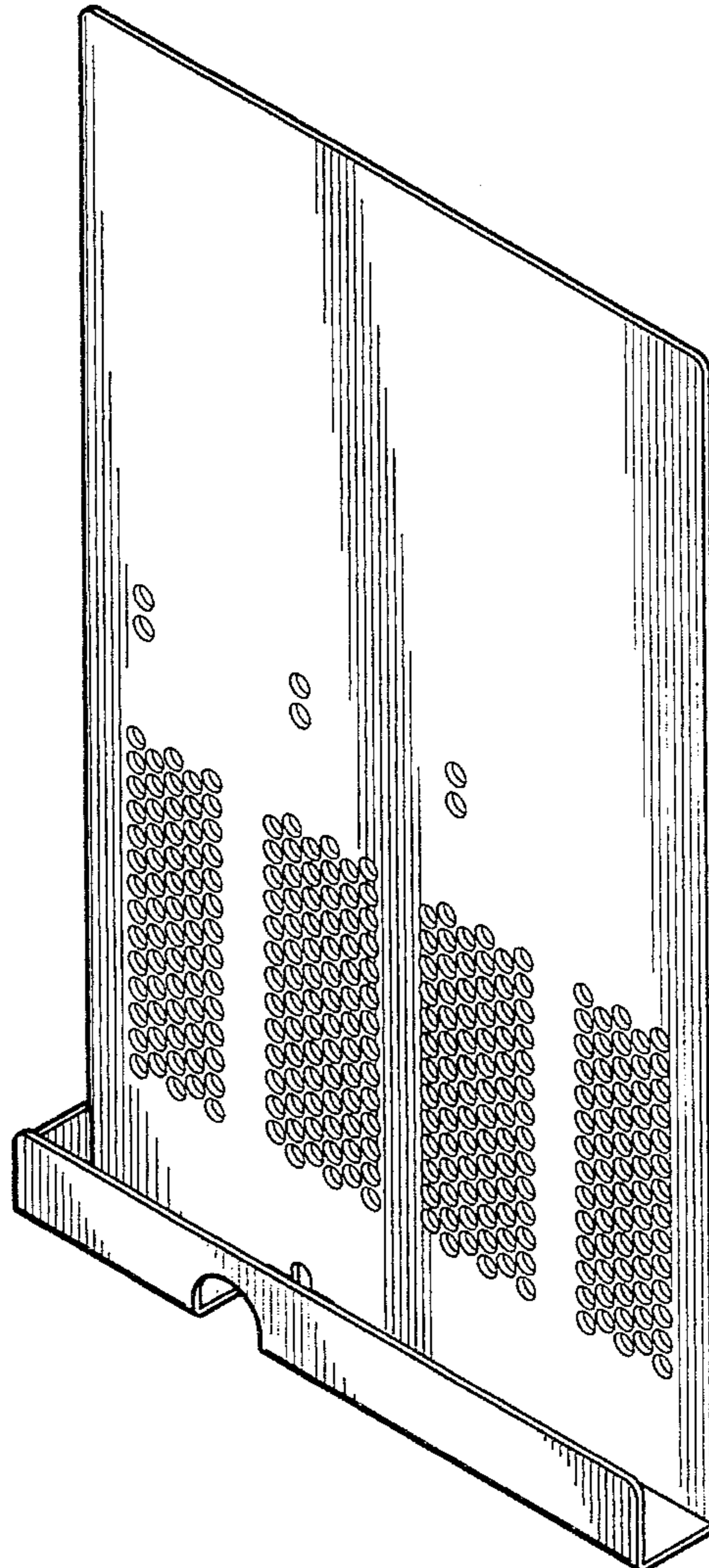
FIG. 3 is a bottom plan view thereof.

[56] References Cited

U.S. PATENT DOCUMENTS

D. 190,233 5/1961 Spadaro D13/177

1 Claim, 1 Drawing Sheet



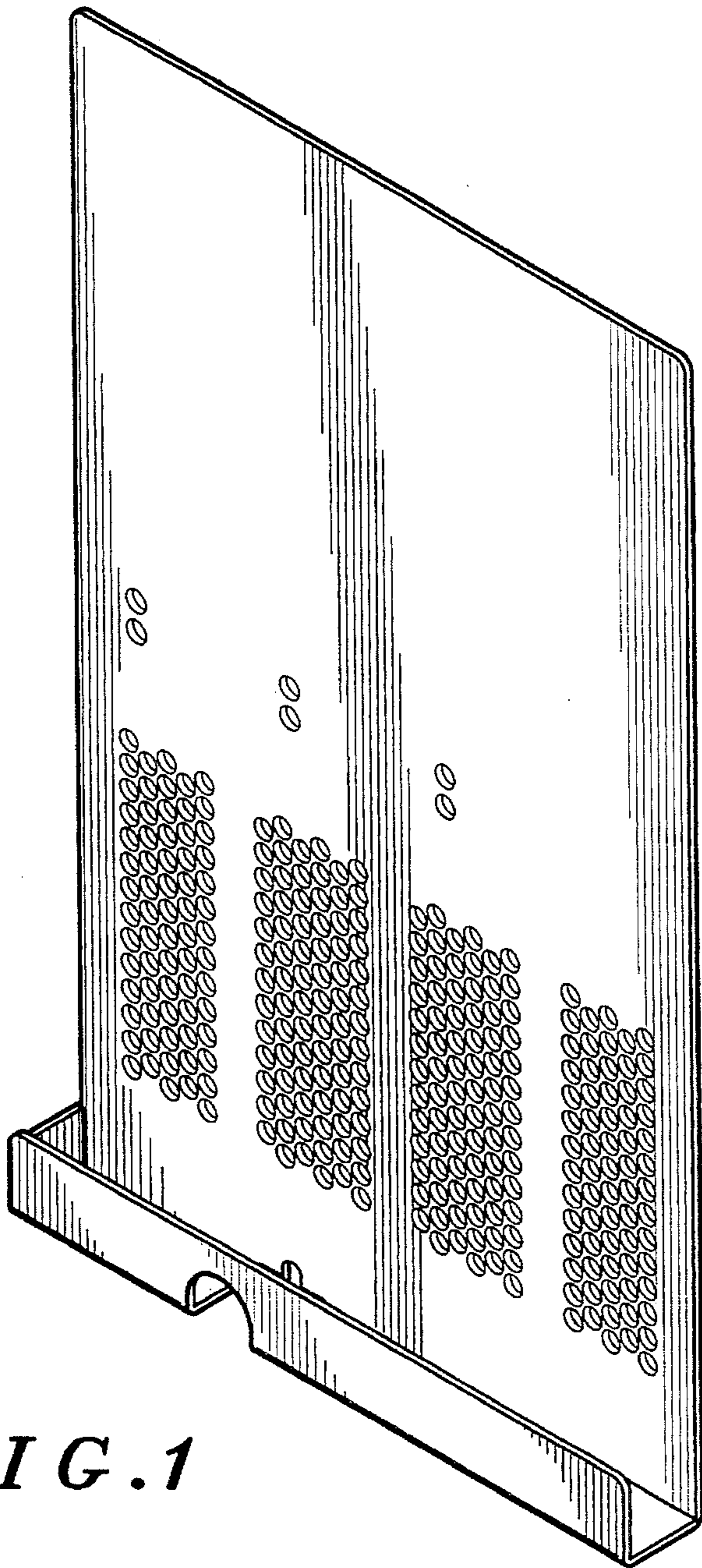


FIG. 1

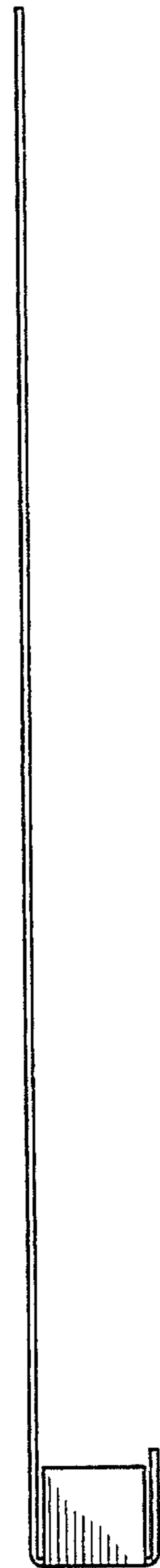


FIG. 2

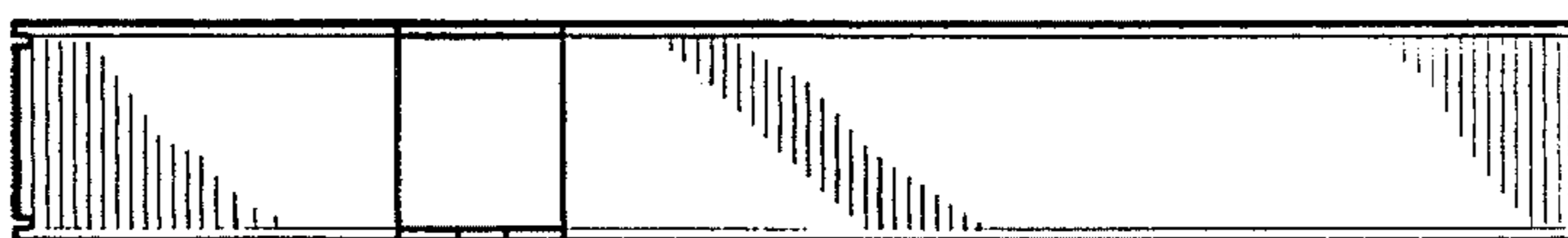


FIG. 3